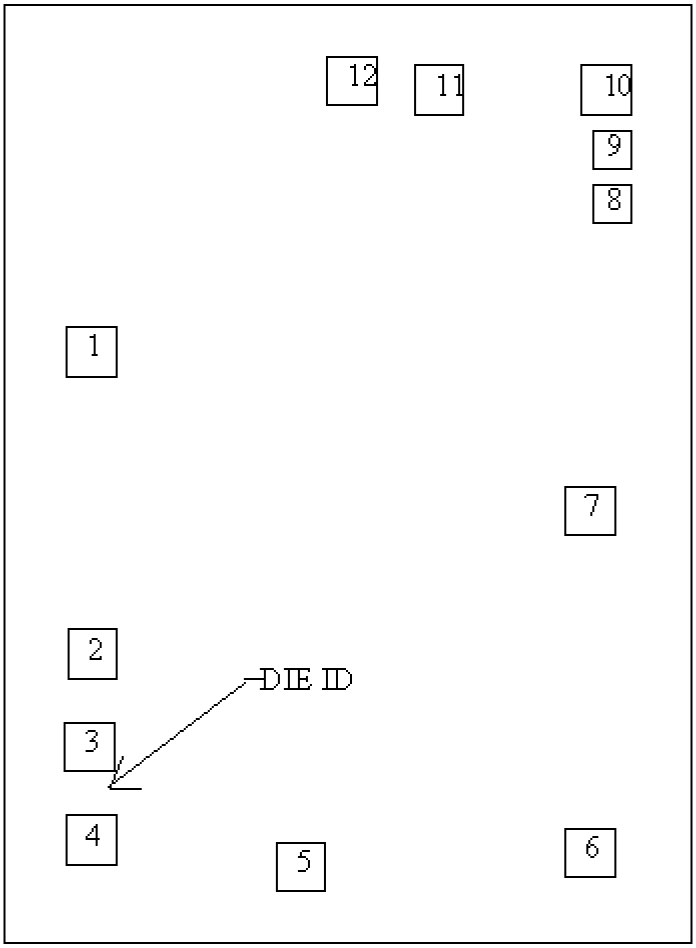
DS16F95 MDS MCD1160A
EIA-485/EIA-422A DIFFERENTIAL BUS TRANSCEIVERS

January 12,2009

DIE LAYOUT (Z-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	M176Z	Bond Pad Opening Size (min)	114µm x 114µm
Die Step	Z	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	NITRIDE
Wafer Diameter	125mm	Back Side Metal	Bare Back
Die Size (Drawn)	1600µm x 2184µm 63.0mils x 86.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	215µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (Z -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
R0	1	-596	285	114	x	114
/RE	2	-593	-420	114	x	114
DE	3	-602	-637	114	x	114
DI	4	-596	-853	114	x	114
GND	5	-110	-916	114	x	114
IN/OUT A	6	563	-883	114	x	114
IN/OUT B	7	563	-85	114	x	114
NC	8	615	628	89	x	89
NC	9	615	755	89	x	89
NC	10	602	895	114	x	114
NC	11	211	894	114	x	114
VCC	12	9	916	114	x	114

Notes

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